Overview

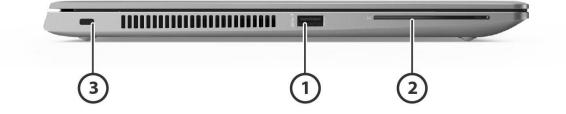
HP ZBook 14u G5 Mobile Workstation



Front



Overview

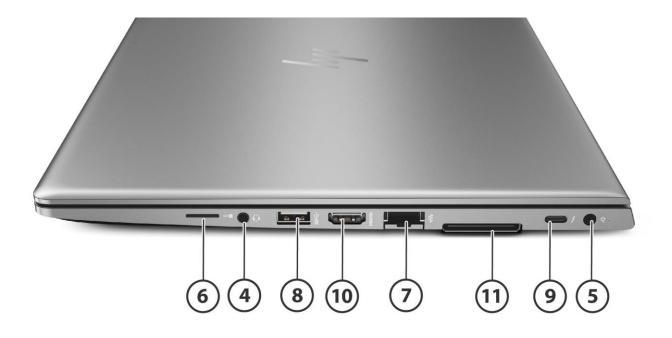


Left

- 1. 1 USB 3.0 (charging)
- 2. 1 smart card reader
- 3. Security lock slot



Overview



Right

- 4. 1 headphone/microphone combo
- 5. 1 power connector
- 6. 1 UHS-II SD card reader
- 7. 1 Ethernet port (RJ-45)

- 8. 1 USB 3.0
- 9. Thunderbolt 3™
- 10. 1 HDMI port
- 11. Side Docking connector



Overview

At A Glance

- Windows 10 editions, or FreeDOS
- Value performance form factor and thinner industrial design than previous generation workstation grade products.
- Thin & light value performance industrial design, Casted magnesium-reinforced chassis, top cover frame features soft touch paint with lightweight aluminum insert anodized in HP's new "Turbo Silver" color. Backlight keyboard in full aluminum deck with magnesium bottom reinforcement, chemically strengthened glass touchpad, and updated system functions indicators. HP Spill Resistant Collaboration Keyboard with Durakeys, touchpad buttons with Duracoat finish...
- Designed to pass military standard MIL-STD-810G testing*.
- Workstation-caliber AMD Radeon Pro[™] discrete graphics: AMD Radeon Pro[™] WX3100 (2 GB dedicated GDDR5); AMD Enduro[™] graphics technology.
- ISV certified to provide fast and reliable performance with workstation applications, including manipulation of 3D textures
- Choice of 8th generation Intel[®] Core[™] i7 and i5 processors
- Intel[®] Core[™] i7 with vPro[™] and Core[™] i5 with vPro[™] technology (optional)
- HP Performance Advisor for optimal configuration, compatibility and performance
- Up to two SODIMMs, for system memory up to 32GB
- Supports up to 3 independent displays via internal LCD Panel, system DisplayPort[™], system VGA, or using the HP UltraSlim Docking Station or HP Thunderbolt Docking Station. Supports DisplayPort[™] 1.2 monitors.
- Bang and Olufsen audio optimized for high fidelity audio with immersive surround sound with deep, rich bass and crystal clear dialog without distortion at high volume
- 3-cell (50 WHr) HP Long Life Battery
- 2 discrete buttons with LED indicator for convenient one touch access: Wireless On/Off, Volume Mute
- Widescreen 14-inch diagonal anti-glare LED-backlit display:
- FHD (1920x1080) ultrawide viewing angle, FHD Touch (1920x1080) standard viewing angle, FHD Touch (1920x1080) standard viewing angle w/ SureView privacy technology, UHD (3840x2160) ultrawide viewing angle
- Supports wireless LAN and wireless WAN options for connectivity on the go.
- One dedicated drive slots. (1) M.2 slot
- Security features including HP Client Security Manager, with central management
- Low halogen, ENERGY STAR[®] certified and EPEAT[®] TBD registered in the U.S. EPEAT[®] status varies by country- please see epeat.net.
- HP BIOS self-healing technology including HP Sure Start to prevent, detect, and remedy known and unknown BIOS attacks.

* MIL STD 810G testing is pending and is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Features

OPERATING SYSTEM

Preinstalled OS	Windows 10 Pro 64*
	Windows 10 Home 64 High End*

FreeDOS 2.0

Supported OS Windows 10 Enterprise 64*

* Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com

NOTE: Your product does not support Windows 8 or Windows 7 In accordance with Microsoft's support policy, HP does not support the Windows[®] 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows[®] 8 or Windows 7 drivers on http://www.support.hp.com

PROCESSOR*

7th Generation Intel® Core™ i5 7300U (2.6 GHz, 3 MB cache, 2 cores) * Up to 3.5 GHz with Intel® Turbo Boost Technology 7th Generation Intel® Core™ i5 7200U (2.5 GHz, 3 MB cache, 2 cores) * Up to 3.1 GHz with Intel® Turbo Boost Technology 8th Generation Intel® Core™ i7 8650U (1.9 GHz, 8 MB cache, 4 cores) * Up to 4.2 GHz with Intel® Turbo Boost Technology 8th Generation Intel® Core™ i7 8550U (1.8 GHz, 8 MB cache, 4 cores) * Up to 4.0 GHz with Intel® Turbo Boost Technology 8th Generation Intel® Core™ i5 8350U (1.7 GHz, 6 MB cache, 4 cores) * Up to 3.6 GHz with Intel® Turbo Boost Technology 8th Generation Intel® Core™ i5 8250U (1.6 GHz, 6 MB cache, 4 cores) * Up to 3.4 GHz with Intel® Turbo Boost Technology

* Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

Also note that the Intel[®] Turbo Boost is based on max GHz for a single core.



Features

CHIPSET

Intel® Kaby Lake Chipset integrated with processor

INTEL® CORE™ I5 WITH VPRO/CORE I7 WITH VPRO TECHNOLOGY CAPABLE

Intel[®] Core[™] i5 with vPro[™] and Core[™] i7 with vPro[™] technology is a selectable feature that is available on units configured with select processors, a qualified Intel[®] Centrino[®] WLAN module and a preinstalled Windows operating system. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel Active Management Technology (iAMT) offers built-in manageability and proactive security for networked mobile workstations, even when they are powered off* or when the operating system is inoperable. It can help identify threats before they reach the network, isolate infected systems, and update mobile workstations regardless of their power state.

* Requires a Windows operating system, network hardware and software, connection with a power source, and a direct (non-VPN) corporate network connection which is either cable or wireless LAN.

NOTE: Some functionality of Intel[®] Core[™] i5 with vPro[™]/Core[™] i7 with vPro[™] technology, such as Intel Active Management technology and Intel Virtualization technology, requires additional third- party software in order to run. Availability of future "virtual appliances" applications for Intel[®] Core[™] i5 with vPro[™]/Core[™] i7 with vPro[™] technology is dependent on third- party software providers. Compatibility with future "virtual appliances" is yet to be determined.

GRAPHICS

Intel[®] UHD 620 Graphics* AMD Radeon Pro[™] WX3100 (2 GB dedicated GDDR5) ** Microsoft DirectX[®] 12 (Shader Model 5.0) and OpenGL[®] 4.3capable AMD Enduro[™] Technology supported.

* HD content required to view HD images

** Supports up to 3 independent displays via internal LCD Panel, system DisplayPort™, system VGA, or using the HP UltraSlim Docking Station DisplayPort™ and VGA ports (sold separately).

DISPLAY

Internal

14.0" diagonal LED backlit FHD UWVA eDP anti-glare (1920 x 1080)

- 14.0" diagonal LED backlit FHD UWVA eDP+PSR anti-glare (1920 x 1080)
- 14.0" diagonal Touch LED-backlit FHD UWVA eDP (1920 x 1080)
- 14.0" diagonal Touch LED-backlit FHD UWVA eDP+PSR, anti-glare + SureView Privacy filter (1920 x 1080)
- 14.0" diagonal LED backlit UHD UWVA eDP+PSR (3840 x 2160)

External

Up to 30-bit (2^30) per pixel "Deep Color" (total of 1,073,741,824 color variations)

DisplayPort™ w/MST (Multi-stream Transport)

Supports resolutions up to UHD 3840 x 2160, 24/30-bit color depth at 60 Hz, and WUXGA (1920 x 1200) monitors, with 24/30-bit color depth up to 120 Hz.



Features

DisplayPort™ Features

 Multi-stream Transport (MST): Multi-stream Transport is a DisplayPort[™] 1.2 feature that allows daisy chaining of DisplayPort[™] 1.2 monitors (requires monitor with DisplayPort[™] 1.2 MST capability), or the use of DisplayPort[™] 1.2 hubs with MST to achieve a maximum of 3 active displays.

DVI-D (single link)

DVI support requires a DP-to-DVI adapter (sold separately). Dual-Link DVI is supported with an active USB powered adapter (sold separately).

NOTE: Resolutions are dependent upon monitor capability, and resolution and color depth settings.

STORAGE AND DRIVES

Primary Storage Bay

M.2 SATA SED SSD 512GB SATA-3 SS TLC SSD FIPS-140-2

HP Z Turbo Drive (NVMe PCIe SSD) 256GB PCIe Gen3x4 (NVMe) TLC Solid State Drive 512GB PCIe Gen3x4 (NVMe) TLC Solid State Drive 1TB PCIe Gen3x4 (NVMe) TLC Solid State Drive 256GB PCIe Gen3x4 (NVMe) TLC Solid State Drive Opal 2 512GB PCIe Gen3x4 (NVMe) TLC Solid State Drive Opal 2 256GB PCIe Gen3x4 (NVMe) MLC Solid State Drive 512GB PCIe Gen3x4 (NVMe) MLC Solid State Drive 1TB PCIe Gen3x4 (NVMe) MLC Solid State Drive

* For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to up to 30 GB (for Windows 10) disk is reserved for system recovery software.



Features

DRIVE CONTROLLERS

M.2 Storage Bay (SATA):
HP Z Turbo Drive:
RAID:

SATA-3 for SSD PCIe NVMe SSD Not supported

NOTE: Raid 0, 1 supported only on SATA drives.

MEMORY

Standard

32 GB DDR4 1.2V Non ECC SDRAM (Transfer rates up to 2400MT/s) Two SODIMM slots supporting dual-channel memory 4 GB, 8GB and 16 GB SODIMMs

Maximum

Upgradeable to 32768 MB with optional 16384 MB SODIMMs in 2 slots

Dual-channel

Maximized dual-channel performance requires SODIMMs of the same size and speed in both memory channels.

* Maximum memory capacities assume Windows 64-bit operating systems or Linux. With Windows 32-bit operating systems, memory above 3 GB may not all be available due to system resource requirements.

NOTE: Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

Communications

Intel[®] I219-LM Gigabit* Network Connection (vPro configurations) Intel[®] I219-V Gigabit* Network Connection (non-vPro configurations)

* The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

Wireless

Secure, integrated wireless LAN and wireless WAN options featuring support for the latest industry standards. Broadband Wireless (WWAN) requires a Windows operating system and is available in select countries as a standard, factory configurable feature only. Integrated Bluetooth is also available (factory configurable only) combined with the supported wireless LAN option.

802.11 Wireless LAN*

Intel[®] Dual Band Wireless-AC 8265 802.11 a/b/g/n/ac (2x2) WiFi + Bluetooth 4.2 Combo Adaptor* (vPro) Intel[®] Dual Band Wireless-AC 8265 802.11 a/b/g/n/ac (2x2) WiFi + Bluetooth 4.2 Combo Adaptor* (non-vPro)

Wireless WAN - Mobile Broadband **



Features

HP lt4120 Qualcomm[®] Snapdragon™ X5 LTE Mobile Broadband Module (optional) HP lt4132, LTE/HSPA+ 4G Mobile Broadband Module (optional) HP hs3210 HSPA+ Mobile Broadband Module (optional)

Near Field Communications (NFC)

HP Module with NXP NFC Controller NPC100

* Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.

** WWAN use requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, and in all regions.

AUDIO/MULTIMEDIA

Audio

Bang and Olufsen audio Integrated stereo speakers Integrated microphone (dual-microphone array when equipped with optional webcam) Button for volume mute; function keys for volume up and down Combo mic-in / stereo headphone-out jack

Webcam

720 HD webcam with IR (Near infrared imaging - optional)

- Microsoft Hello Certification: Microsoft face authentication in Windows 10 is an enterprise-grade identity verification mechanism
- Microsoft Skype for Business1 Certified
- HD format (widescreen 16:9)
- · Supports videoconferencing and still image capture
- High quality fixed focus lens
- Video capture at various resolutions up to 1280x720 resolution (720p) and up to 30fps
- · M-JPEG compression supports higher frame rates for video capture and videoconferencing
- Improved low light sensitivity
 - Improved dynamic range
- * HD content required to view HD images.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

Optional backlit keyboard with Function key control to toggle backlit brightness setting - off/full/half brightness The HP spill-resistant keyboard is designed using a thin layer of Mylar film under the keyboard and a drain system that funnels fluid through a hole in the bottom of the notebook. This minimizes the risk of damage to sensitive components underneath. The 86-key compatible keyboard features a full-pitch key layout with desktop keyboard features, such as editing keys, both left and right control and alt keys, function keys, and 18.7 x 18.4 mm key pitch (center-to-center spacing). U.S. and International key layouts are available. Other features include hot keys for instant access to power conservation and brightness.



Features

Pointing Devices

Point stick with two additional point stick buttons Image sensor Clickpad for enhanced performance and improved precision on scroll and gesture

Function Keys

Function keys provide control of the following features: standby mode, external display, volume down, volume up, and display brightness.

- F1 Display Switching
- F2 Blank or SureView
- F3 Brightness Down
- F4 Brightness Up
- F5 Audio Mute
- F6 Volume Down
- F7 Volume Up
- F8 Mic Mute
- F9 Backlit Toggle
- F10 Numlk
- F11 Wireless
- F12 Calendar
- >Share/Present
 >Call Answer
- Call End

SOFTWARE AND SECURITY

Preinstalled Software with Windows Operating System

BIOS

HP BIOSphere Gen3¹ HP Sure Start Gen3² HP DriveLock | HP Automatic DriveLock BIOS Update via Network Master Boot Record Security Power On Authentication Secure Erase³ Absolute Persistence Module⁴ Pre-boot Authentication

Multi Media Cyberlink Power MediaPlayer CMIT

Communication / Connectivity

HP Mobile Connect Pro⁵ Native Miracast Support⁶ HP LAN-WLAN Protection HP MAC Address Manager (select models only) HP Wireless Wakeup (select models only) HP SureConnect

HP Value Add Software

HP 3D DriveGuard 6 HP ePrint Driver + JetAdvantage⁷



Features

HP Hotkey Support HP Recovery Manager HP Jumpstart HP Support Assistant¹² HP Noise Cancellation Software HP Performance Advisor HP Remote Graphics Software HP Velocity

Microsoft Products

Buy Office Bing Search Skype⁸

Manageability

HP Driver Packs⁹ HP SoftPaq Download Manager (SDM) HP System Software Manager (SSM)⁹ HP BIOS Config Utility (BCU)⁹ HP Client Catalog⁹ HP Manageability Integration Kit for Microsoft SCCM¹⁰ HP Image Assistant LANDESK Management¹¹

For more information on HP Client Management Solutions refer to: http://www.hp.com/go/clientmanagement.

Client Security Software

- HP Client Security Suite Gen3¹³
- HP Security Manager (including Credential Manager and Password Manager)
- HP Fingerprint Sensor
- Power On Authentication
- Device Access Manager
- Microsoft Defender ¹⁴
- HP WorkWise¹⁵

Standard

For Windows 10, Trusted Platform Module (TPM) 2.0 (Infineon SLB9670). Common Criteria EAL4+ Certified. HP Fingerprint Reader

For more information on HP Client Security Software Suite, refer to http://www.hp.com/go/clientsecurity.

- 1. Requires Intel[®] 7th generation processors
- 2. Available on HP Elite and Z products equipped with Intel® 7th generation processors.
- 3. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88. Supported on Elite and Z platforms with BIOS version F.O3 or higher
- 4. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
- 5. HP Mobile Connect Pro is only available on preconfigured devices with WWAN. For geographic availability refer to http://www.hp.com/go/mobileconnect

HP ZBook 14u G5 Mobile Workstation

QuickSpecs

Features

- 6. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming media players that also support Miracast. You can use Miracast to share what you're doing on your PC and present a slide show. For more information: http://windows.microsoft.com/en-us/windows-8/project-wireless-screen-miracast
- 7. Requires an Internet connection to HP web-enabled printer and HP ePrint account registration (for a list of eligible printers, supported documents and image types and other HP ePrint details, see http://www.hp.com/go/eprintcenter). Separately purchased data plans or usage fees may apply. Print times and connection speeds may vary.
- 8. Skype is not offered in China.
- 9. Not preinstalled, however available for download at http://www.hp.com/go/clientmanagement
- 10. HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html
- 11. Subscription required.
- 12. Requires Windows and Internet Access
- 13. Requires Windows and Intel® 7th generation processors.
- 14. Opt in and internet connection required for updates.
- 15. HP WorkWise smartphone app is available as a free download on the App Store and Google Play. As of September 2017, HP WorkWise will no longer support iOS or iPhone[®] devices.

Workstation ISV Certifications

Find the latest list of certifications at: http://www.hp.com/go/isv

HP Remote Graphics Software

The remote desktop solution for serious workstation users and their most demanding applications. Download at: http://www.hp.com/go/RGS

HP Performance Advisor

Get the most out of your HP Workstation on day one—and every day thereafter. Designed for all users regardless of technical background, this ultra-savvy software wizard is the simplest and most effective way to make sure your computer is always operating at its optimum potential. Download at: http://www.hp.com/go/performanceadvisor

Security

See Software section above.

Other Standard Security Features

Integrated Smart Card Reader One-Step Logon Security lock slot Support for Intel® AT

Optional Security Features

HP Fingerprint Sensor (optional)

Absolute Data Protect* with GPS Tracking - Subscription based security solution providing the ability to track, initiate physical recovery, conduct asset management, and perform remote data delete by utilizing GPS technology. GPS functionality requires HP Mobile Broadband Module.

* The Absolute Data Protect agent is shipped turned off, and must be activated by customers when they purchase a subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S.

HP CENTRAL MANAGEMENT



Features

HP offers a variety of scalable hardware, software, and BIOS-based security features to help you defend your organization against viruses and other threats. These integrated security features safeguard what matters to you the most - your data, device and identity. Now, be confident your fleet of devices is protected in multiple layers of HP Client Security protection.

HP BIOS Protection keeps you up and running with enhanced protection against virus attacks and other threats. And if the BIOS is accidently compromised, the auto recovery feature automatically restores it to its fully functional state.

HP Sure Start detects and negates a BIOS attack with automatic recovery of the BIOS even when the installation is accidentally compromised (i.e. power outage). When HP Sure Start heals the BIOS an event log is generated that an IT administrator can retrieve so the business is aware of a BIOS attack. Golden copy of BIOS is stored in protected nonvolatile memory providing redundant, hardware-based protection against a new generation of attacks.

An optional fingerprint reader and integrated Smart Card Reader help keep your identity secure. The security cable slot helps keep your notebook physically secure.

You can even permanently destroy data on your hard drive in preparation for your system disposal or redeployment with Secure Erase.



Features

POWER

Power Supply HP 65W Slim Smart AC Adapter

Primary Battery HP 3-cell Long Life Polymer Battery (50 WHr)

Battery Life Battery life up to 10 hours *

System Standby Time Up to TBD weeks**

*Battery life will vary depending on the product model, configuration, loaded applications, features, use, wireless functionality and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See MobileMark14 battery benchmark https://bapco.com/products/mobilemark-2014/ for additional details. ** Standby life will vary depending on various factors including battery, Memory, CPU, EC and LAN chip. The maximum capacity of the battery will naturally decrease with time and usage.

Power Conservation

AMD[®] Polaris™ Technology Hibernation Standby ACPI compliance

ENVIRONMENTAL

US ENERGY STAR[®] IT ECO declaration EPEAT[®] registered where applicable. EPEAT[®] registration varies by country. See http://www.epeat.net for registration status by country. See HP's 3rd party option store for solar energy accessory www.hp.com/go/options.

NOTE: This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks.

WEIGHTS & DIMENSIONS

WeightStarting at3.Dimensions (w x d x h)

3.27 lb (1.48 kg)

12.84 x 9.22 x 0.71 in

326 x 234.3 x 17.9 mm

NOTE: Height varies depending upon where on the notebook the measurement is made. Weight varies by configuration and components. Weight includes 3 cell 46Whr battery, without hard drive and with 256 GB Z Turbo Drive (PCIe SSD).



Features

PORTS/SLOTS

Ports

Left side:

(1) USB 3.0 Charging Port (1) Security lock slot

Right side:

(1) Thunderbolt 3[™]
(1) USB 3.0 Port
(1) Headphone/Microphone Combo
(1) RJ-45 / Ethernet
(1) Side Docking connector
(1) Power connector

Digital Media Slots

(1) SD UHS-II Flash Media slot – Supports next generation SD (Secure Digital), backward compatible to SDHC, SDXC
 (1) Integrated Smart Card Reader (Compatible with ISO 7816 compliant Smart Cards PC/SC interface support)

SERVICE AND SUPPORT

Limited 3-year or 1-year limited warranty options available, depending on country. Batteries have the same 1-year or 3-year limited warranty as the platform. Optional¹ HP Care Pack Services are extended service contracts which go beyond your standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at http://www.hp.com/go/cpc.

 Sold separately or as an optional feature. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product. Consult your local HP Customer Support Center for details.



Technical Specifications – System Unit

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	Nominal Operating Voltage	19.5 V dc @ 3.3 A	
-	Average Operating Power	r	Windows® 10 (64-bit)
		AMD FirePro™ Graphics	
	Max Operating Power	< 65 W	
Temperature	Operating	32° to 95° F (0° to 35° C) (not writing optical) 41° to 95° F (5° to 35° C) (writing optical)	
	Non-operating	-4° to 140° F (-20° to 60° C)	
Relative Humidity	Operating	10% to 90%, non-condensing	
	Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb t	emperature
Shock	Operating	40 G, 2 ms, half-sine	
	Non-operating	200 G, 2 ms, half-sine	
Random Vibration	Operating	0.75 grms	
	Non-operating	1.50 grms	
Altitude (unpressurized)	Operating	-50 to 10,000 ft. (-15.24 to 3,048 m)	
	Non-operating	-50 to 15,000 ft. (-15.24 to 12,192 m)	
Planned Industry	UL	Yes	
Standard Certifications	CSA	Yes	
Certifications	FCC Compliance	Yes	
	ENERGY STAR®	Select models*	
	EPEAT®	Gold target**	
	ICES	Yes	
	Australia / NZ A-Tick Compliance	Yes	
	כככ	Yes	
	Japan VCCI Compliance	Yes	
	КСС	Yes	
	BSMI	Yes	
	CE Marking Compliance	Yes	
	MIL STD***	Planned	

* Configurations of the HP ZBook 14u G5 that are ENERGY STAR[®] certified are identified as HP ZBook 14u G5 ENERGY STAR[®] on HP websites and on http://www.energystar.gov.

** EPEAT registration varies by country. See http://www.epeat.net for registration status by country.

EPEAT status listed above applies to U.S.

*** MIL STD 810G testing is pending and is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Damage under the MIL STD test conditions or any accidental damage requires an optional HP Accidental Damage Protection Care Pack.

For accessibility information on HP products, please visit: http://www.hp.com/accessibility.



Technical Specifications – Displays

DISPLAYS

14.0" diagonal LED backlight FHD UWVA IPS eDP Anti-glare (1920 x 1080)	Dimensions (W × H) Active Area Weight Surface Treatment Contrast Ratio Refresh Rate Brightness	315.41 x 196.17 max. (w/ 309.37 x 174.02 (mm) 225g max Anti-glare 600:1 (typical) 60 Hz 340 nits	
	Pixel Resolution	Format Configuration	1920 x 1080 (FHD)
	Backlight	LED	RGB
	PPI	157	
	Viewing Angle	UWVA 85/85/85/85	
14.0" diagonal LED backlight FHD SVA eDP	Outline Dimensions (W x H x D)	320.9 x 205.6 x 3 (mm) ma	ах
Anti-glare (1920 x 1080)	Active Area	309.40 x 173.95 (mm)	
	Weight	270 g max	
	Diagonal Size	14.0 (inch)	
	Surface Treatment	Anti-Glare (AG)	
	Contrast Ratio	300:1 (typical)	
	Refresh Rate	60 Hz	
	Brightness	300 nits	
	Pixel Resolution	Format Configuration	1920 x 1080 (FHD) RGB
	Interface	eDP 1.2	
	PPI	157	
	Viewing Angle	SVA 45/45/25/35	
14.0" diagonal LED backlight FHD SVA eDP	Outline Dimensions (W x H x D)	320.9 x 205.6 x 3 (mm) ma	ах
(1920 x 1080) Touch with Camera	Active Area	309.40 x 173.95 (mm)	
	Weight	270 g max	
	Diagonal Size	14.0 (inch)	
	Surface Treatment	Anti-smudge/fingerprint c	oating
	Contrast Ratio	300:1 (typical)	
	Touch Enabled	Yes	
	TSP Type	Capacitive	
	Refresh Rate	60 Hz	
	Brightness	300 nits	
	Pixel Resolution	Format	1920 x 1080 (FHD)

Technical Specifications – Displays

		Configuration	RGB
	Interface	eDP 1.2	
	LCD Mode	TN	
	PPI	157	
	Viewing Angle	SVA 45/45/25/35	
14.0" diagonal LED	Active Area (W × H)	309.4 x 173.95 (mm)	
backlight HD SVA eDP	Dimensions (W × H)	320.9 x 205.6 (mm) max	
(1366 x 768)	Weight	290 g max	
	Surface Treatment	Anti-Glare (AG)	
	Contrast Ratio	300:1 (typ)	
	Refresh Rate	60 Hz	
	Brightness	220 nits	
	Pixel Resolution	Format	1920 x 1080 (FHD)
		Configuration	RGB
	Backlight	LED	
	PPI	112	
	Viewing Angle	SVA 45/45/25/35	

Technical Specifications – Storage

STORAGE AND DRIVES*

JI ORACE AND DRIV			
500 GB 5400rpm Self	Drive Weight	0.21 lbs (95 g)	
Encrypting Drive (FIPS- 140-2) (Opal 2)	Capacity	500 GB	
	Height	0.28 in (7 mm)	
	Width	2.75 in (69.85 mm)	
	Interface	ATA-8, SATA 3.0	
	Transfer Rate	Synchronous (maximum)	600 MB/s
	Seek Time	Single Track	1.5 ms
	(typical reads, including	Average	12 ms
	settling)	Maximum	21 ms
	Cache	Up to 32MB	
	Rotational Speed	7200 rpm	
	Logical Blocks	976,773,168	
	Operating Temperature	32° to 140° F (0° to 60° C) [top cover temp]
	Features	ATA Security; TCG Opal 2.x,	, FIPS, S.M.A.R.T., NCQ, Ultra DMA
500 GB 7200rpm	Drive Weight	0.20 lbs (92 g) ~ 0.21 lbs (9	95 g)
Hard Drive	Capacity	500 GB	
	Height	0.28 in (7 mm)	
	Width	2.75 in (69.85 mm)	
	Interface	ATA-8, SATA 3.0	
	Transfer Rate	Synchronous (maximum)	1.5 ms ~ 2.0 ms
	Seek Time	Single Track	11 ms ~ 13 ms
	(typical reads, including	Average	18 ms ~ 22 ms
	settling)	Maximum	1.5 ms ~ 2.0 ms
	Cache	Up to 32 MB	
	Rotational Speed	7200 rpm	
	Logical Blocks	976,773,168	
	Operating Temperature	32° to 140° F (0° to 60° C) [case temp]
	Features	ATA Security, S.M.A.R.T., N	CQ, Ultra DMA
500 GB 7200rpm Self-	Drive Weight	0.21 lbs (95 g)	
Encrypting Drive (Opal 2)	Capacity	500 GB	
	Height	0.28 in (7 mm)	
	Width	2.75 in (69.85 mm)	
	Interface	ATA-8, SATA 3.0	
	Transfer Rate	Synchronous (maximum)	600 MB/s
	Seek Time	Single Track	1.5 ms
	(typical reads, including	Average	12 ms
	settling)	Maximum	21 ms
	Cache	Up to 32MB	
	Rotational Speed	7200rpm	
	Logical Blocks	976,773,168	
	Operating Temperature	32° to 140° F (0° to 60° C) [top cover temp]
	Features	ATA Security; TCG Opal 2.x,	, S.M.A.R.T., NCQ, Ultra DMA
1 TB 5400rpm Hard Drive	Drive Weight	0.21 lbs (94 g)- 0.21 lbs (9	5 g)



Technical Specifications – Storage

Height0.28 in (7 mm) Width2.75 in (68.95 mm) InterfaceNote that the the the the the the the the the th		Capacity	1 TB	
With Interface2.75 in (69.85 mm) 00 MB/sInterfaceSeek Time (typical reads, including seek Time) 00 MB/sSeek Time (typical reads, including setting) $Nerage$ Maximum 12 ms-13 msGacheUb 032/MB 12 ms-13 msBotational Speed 400 rpm 12 ms-13 msGacheUb 032/MB $1953, 252, 168$ Operating Temperatur 32^{10} 1040°F (0° to 60° \ [$seet Temp]$ FeaturesA4Security, SM.A.R.T., NCQ, Uttra DMABotational Speed 4300 rpmHight0.198 lbs (90 g) - 0.20 lbs ($Seet$ Tem)Bota Specific S				
Interface ATA-8, SATA 3.0 Image Rate Synchronos (maximu) 600 MB/s Seek Time Single Track 2ms Seek Time Verage 12 ms Verage 12 ms 12 ms Baid Social Mode 1980 - 22 ms 12 ms Social Block 1983 - 32 ms 12 ms Fototional Speed 1983 - 32 ms 12 ms Social Block 1983 - 32 ms 12 ms Gochen Units 1983 - 32 ms 12 ms Social Block Capacity 00 GB 12 ms Heigh 0.28 in (7 mm) 12 ms 12 ms Width 0.28 in (7 mm) 10 ms 12 ms Width 2.75 in (69.85 mm) 12 ms < 13 ms Stational Speed Social Block 12 ms < 13 ms Stational Speed Social Tack 12 ms < 13 ms Stational Speed Social maximu 12 ms < 13 ms Stational Speed Social maximu 12 ms < 13 ms Stational Speed Social maximu 12 ms < 13 ms		-		
Fransfer Name Sindromos (maximu) Sindmatu Seek Time (typical reads, including) Namamu 12 ms-13 ms Maximu 12 ms-13 ms 12 ms-13 ms Cache Up to 32MB 12 ms-12 ms Facture 12 ms-13 ms 12 ms-12 ms Digited Blocks 5400 rpm 12 ms-12 ms Factures 21 to 140° F0° to 60° L = set temp 12 ms Factures 0.1981 b(30 of 0 - 0.20 U = set temp 12 ms Factures 0.1981 b(30 of 0 - 0.20 U = set temp 12 ms Factures 0.1981 b(30 of 0 - 0.20 U = set temp 12 ms Factures 0.1981 b(30 of 0 - 0.20 U = set temp 12 ms Factures 0.1981 b(30 of 0 - 0.20 U = set temp 12 ms Factures 0.1981 b(30 of 0 - 0.20 U = set temp 12 ms Height 0.298 if 0 rm 12 ms 12 ms Tarsfer Rate Shofe Cardinum 10 ms 12 ms Stack Time Singe Tarci 12 ms 12 ms 12 ms Stack Time Singe Tarci 12 ms 12 ms 12 ms 12 ms Stack Time Singe Tarci 12 ms <t< th=""><th></th><th>Interface</th><th></th><th></th></t<>		Interface		
Seek Time (typical reads, includie) Single Tack 2 ms Barban 12 ms-13 ms Settling) Waxman 18 ms-22 ms Barban 18 ms-22 ms Fache 1950 S25, 158 18 ms-22 ms Toperating Temperatu 22* to 140° F (0* to 60° - 1.5* temp] 100 ms Fatures ATA Security, SMA.R.T., V-U, Utra JMA 100 ms Fatures ATA Security, SMA.R.T., V-U, Utra JMA 100 ms Fatures ATA Security, SMA.R.T., V-U, Utra JMA 100 ms Fatures 1028 in (7 mm) 2.9 Vinith 0.28 in (7 mm) 2.9 Heigh 0.28 in (7 mm) 2.9 Interface Sect Time 1.5 ms - 2 ms (typical reads, includid) Average 1.5 ms - 2 ms Sect Time Sect Time 1.2 ms - 2 ms (typical reads, includid) Average 1.2 ms - 2 ms Sect Time Sect Time 1.2 ms - 2 ms (typical reads, includid) Sect Time 1.2 ms - 2 ms Sect Time Sect Time 1.2 ms - 2 ms		Transfer Rate	•	600 MB/s
kerage 12 ms-13 ms Naximum 18 ms-22 ms Rotational Speed 5400 rm Kotational Speed 5400 rm Logical Blocks 1,953,52,168 Operating Temperature 32* to 140°F (0° to 60°) [sase temp] Features 0198 lbs (00 9 - 0.20 lbs: vol.000 lbs: vol.0000 lbs: vol.0000 lbs: vol.000 lbs: vol.000 lbs: vol.000 lbs: vol.		Seek Time	-	
settling) Maximum 18 ms-22 ms Cache Up to 32MB			-	12 ms-13 ms
Soo GB Hybrid, BGB cache Rotational Speed Logical Blocks 1,953,525,168 Operating Temperature Features ATA Security, S.M.A.T., N.U., Ultra DMA O Drive Weight 0.198 lbs (90 0, 0.20 lbs (90 - 0.20 lbs (90		settling)	-	18 ms-22 ms
Soo GB Hybrid, Logical Blocks 1,953,525,168 32° to 140° F (0° to 60° C) [-ase temp] ATA Security, S.M.A.R.T., NCJ, Ultra DMA BG Ga Cabe Capacity 500 GB BG Ga Cabe Capacity 500 GB Height 0.28 in 7 mm) Ultra DMA Height 0.28 in 7 mm) Ultra DMA Width 2,75 in (69.85 mm) 500 MB/s Interface ATA-8, SATA 3.0 500 MB/s Seek Time Single Track 1,5 ms ~ 2 ms Seek Time Single Track 1,2 ms ~ 13 ms Seek Time Single Track 2 ms ~ 13 ms Seek Time Single Track 1,2 ms ~ 13 ms Seek Time Single Track 2 ms ~ 13 ms Seek Time Single Track 2 ms ~ 13 ms Seek Time Single Track 2 ms ~ 13 ms Seek Time Single Track 2 ms ~ 13 ms Seek Time Single Track 2 ms ~ 13 ms Seek Time Single Track 2 ms ~ 13 ms Seek Time Single Track 2 ms ~ 13 ms Seek Time Single Track 2 ms ~ 13 ms Up		Cache	Up to 32MB	
Soo GB Hybrid, BG Cache Operating Temperatun Features 32'to 140° F (0° to 60° ∪ [-sec temp] BG Cache Orive Weight 0.198 b(s (00 g) - 0.20 U ∪ U a DMA BG Cache Soo GB Soo GB Height 0.28 in (7 mm) U Height 2.75 in (69.85 mm) Soo MB/s Interface ATA-8, SATA 3.0 Interface Transfer Rate Single Track 15 ms ~ 2 ms Seek Time Maximum 22 ms ~ 32 ms Seek Time Norto 12 MBK 22 ms ~ 32 ms Forting Torive Sol Orpm 22 ms ~ 32 ms Forting Temperatur Sol Cacorty, SA, AR, J. U Seif-Encrypting Drive Features ATA Security, SA, AR, J. U Gorating Temperatur Sol Cacorty, SA, AR, J. U U Seif-Encrypting Drive Maximum Maximum Sequential Maximum Sequential Moreweight O.02 lo (03 mi)		Rotational Speed	5400 rpm	
Soo GB Hybrid, Features ATA Security, S.M.A.R.T., N∪, Ultra DMA BGB cache Drive Weight 0.198 lbs (90 g) ~ 0.20 lbs (92 g) Gapacity 500 GB 500 GB Height 0.28 in (7 mm) 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0		Logical Blocks	1,953,525,168	
S00 GB Hybrid, GB cache Drive Weight 0.198 lbs (90 g) ~ 0.20 lbs (92 g) Gapacity S00 GB Height 0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0 Seek Time Single Track 1.5 ms ~ 2 ms Seek Time Single Track 1.5 ms ~ 2 ms Ktypical reads, including Average 12 ms ~ 13 ms settling) Maximum 22 ms ~ 32 ms Cache Up to 128MB Jms ~ 2 ms ~ 13 ms Settling) Settling Operating Temperature 32° to 140° F (0° to 60° C) [Jms ~ 2 ms ~ 13 ms Setf-Encrypting Drive Operating Temperature 32° to 140° F (0° to 60° C) [Jms ~ 2 ms ~ 32 ms 12 ms ~ 13 ms Setf-Encrypting Drive Operating Temperature 32° to 140° F (0° to 60° C) [Jms ~ 2 ms ~ 13 ms 12 ms ~ 13 ms Setf-Encrypting Drive Operating Temperature 32° to 140° F (0° to 60° C) [Jms ~ 2 ms ~ 13 ms 12 ms ~ 13 ms Setf-Encrypting Drive Operating Temperature 32° to 140° F (0° to 60° C) [Jms ~ 2 ms ~ 13 ms 12 ms ~ 13 ms Width 0.02 lb (10 g) Capacity 256 GB Maximum Sequential Write Read <t< th=""><th></th><th>Operating Temperature</th><th>32° to 140° F (0° to 60° C) [</th><th>case temp]</th></t<>		Operating Temperature	32° to 140° F (0° to 60° C) [case temp]
8 GB cache Capacity 500 GB Height 0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0 Transfer Rate Synchronous (maximum) 600 MB/s Seek Time Single Track 1.5 ms ~ 2 ms Seek Time Single Track 1.5 ms ~ 2 ms Ktypical reads, including Average 12 ms ~ 13 ms settling) Maximum 22 ms ~ 32 ms Cache Up to 128MB Jams ~ 32 ms ~ 32 ms Rotational Speed 5400 rpm Jams ~ 32 ms ~ 32 ms Logical Blocks 976,773,168 Jams ~ 32 ms ~ 32 ms Operating Temperature 32° to 140° F (0° to 60° C) [case temp] Features Features ATA - Scurity, S.M.A.R.T., NCQ, Ultra DMA Jams ~ 32 ms Self-Encrypting Drive Operating Temperature 32° to 140° F (0° to 60° C) [case temp] Jams ~ 32 ms Gapacity 256 GB Algent Jams ~ 32 ms Jams ~ 32 ms Vidth 0.02 lb (10 g) Lapsicitee Lapsicitee Jams ~ 32 ms Gapacity 256 GB Maximum Sequential Write Raeine Self - 500, 118, 1		Features	ATA Security, S.M.A.R.T., N	CQ, Ultra DMA
Height 0.28 in (7 mm) Width 0.27 in (69.85 mm) Interface ATA-8, SATA 3.0 Transfer Rate Synchronous (maximum) 600 MB/s Seek Time Single Track 1.5 ms ~ 2 ms (typical reads, including settling) Maximum 22 ms ~ 32 ms Cache Up to 128MB 22 ms ~ 32 ms Cache Seio to 00° f0° to 60° C) [case temp] 1000 rpm Logical Blocks 976, 773, 168 1000 rpm Operating Temperature 32° to 140° F (0° to 60° C) [case temp] 1000 rpm Features ATA Security, S.M.A.R.T., NCQ, Ultra DMA 1000 rpm Self-Encrypting Drive (Opal 2) TLC Solid State Drive Weight 0.02 lb (10 g) 1000 rpm Gapacity 256 GB 1000 rpm 1000 rpm 1000 rpm Interface ATA Security, S.M.A.R.T., NCQ, Ultra DMA 1000 rpm Gapacity 256 GB 1000 rpm 1000 rpm Interface 0.02 lb (10 g) 1000 rpm 1000 rpm Up to 530 MB/s Up to 530 MB/s Up to 530 MB/s 1000 rpm Up to 530 MB/s Up to 530 MB/s Up to 515 MB/s 10000 r	500 GB Hybrid,	Drive Weight	0.198 lbs (90 g) ~ 0.20 lbs	(92 g)
Number2.75 in (69.85 mm)InterfaceATA-8, SATA 3.0Transfer RateSynchronous (maxium)6:00 MB/sSeek Time (typical reads, includ)Single Track1.5 ms ~ 2 msSeek Time (typical reads, includ)Mainuan2 ms ~ 13 msSeek Time (typical reads, includ)No 12 MB/s2 ms ~ 13 msAuerage0 to 128MB2 ms ~ 13 msSeek Time (typical reads, includ)Seek Time (typical reads, includ)2 ms ~ 13 msAuerage0 to 128MB2 ms ~ 13 msSeek Time (typical reads, includ)Self Or 12 ms2 ms ~ 21 msBatterRotational SpeedS400 rpm2 ms ~ 21 msBatterOperating Temperatu (apacitySelf Or 01 G0 G0 C1 - se temp]TemperatuSelf-Encrypting Drive (fopal 21 LLS Solid) StateOperating Temperatu (Agacity0.02 lb (10 g)- 12 msProfer ManceDrive Weight0.02 lb (10 g)- 12 ms- 12 msHight0.21 ms0.21 ms- 12 ms- 12 msInterface0.22 ms- 22 ms- 22 ms- 22 msInterface0.21 ms- 22 ms- 22 ms- 22 msInterface0.22 ms	8 GB cache	Capacity	500 GB	
Interface ATA-8, SATA 3.0 Transfer Rate Synchronous (maximum) 600 MB/s Seek Time Single Track 1.5 ms ~ 2 ms Seek Time Single Track 12 ms ~13 ms Settling) Average 12 ms ~13 ms Maximum 22 ms ~32 ms 20 ms ~32 ms Cache Up to 128MB		Height	0.28 in (7 mm)	
Fransfer Rate Sinde Track 500 MB/s Seek Time (typical reads, incluid) Singe Track 1.5 m.5 m.2 m.3		Width	2.75 in (69.85 mm)	
Seek Time (typical reads, including settling) Gache Cache Up to 128MB Rotational Speed 5400 rpm Logical Blocks 76,773,168 Operating Temperature 7256 GB M2 2280 SATA-3 Self-Encrypting Drive Features ATA Security, S.M.A.R.T., NCQ, Ultra DMA Drive Weight 0.02 lb (10 g) Capacity 7256 GB View Height 0.02 lb (10 g) Capacity Width 0.87 in (22 mm) Interface Namum Sequential Maximum Sequential Width 0.02 lb (10 g) Capacity Up to 530 MB/s Up to 515 MB/s Cograting Temperature Self-Encrypting Drive Operating Temperature 600 118,192 Capacity <pcapacity< p=""> <pc< th=""><th></th><th>Interface</th><th>ATA-8, SATA 3.0</th><th></th></pc<></pcapacity<>		Interface	ATA-8, SATA 3.0	
Kpjčal reads, includio settling)Average1 cm s-13 ms 2 cm s-32 msKanium2 cm s-32 ms2 cm s-32 msKacheUp to 128MB2 ms s-32 msKational Speed540 rpm540 rpmLogical Blocks976,773,168T msFaturesATA Security, S.M.A.R.T., Vultra DMAT msFatures0.21 b(10 g)T msSelf-Encrypting Drive (Dpal 2) TLC Solid State DriveDrive Weight0.21 b(10 g)Height0.21 b(10 g)T msKate DriveMainum Sequential Nor in (22 mm)T msHeight0.37 in (22 mm)T msHeight0.37 in (22 mm)T msInterfaceMaximum Sequential Nor in (22 mm)Mainum Sequential Write ReadForformanceMaximum Sequential Nor in (23 ms)Minum Sequential Write ReadFaturesAns Sourity, TCG Op3		Transfer Rate	Synchronous (maximum)	600 MB/s
settling) Maximum 22 ms ~ 32 ms Cache Up to 128MB Rotational Speed 5400 rpm Logical Blocks 976,773,168 Operating Temperature 32° to 140° F (0° to 60° C) [case temp] Features ATA Security, S.M.A.R.T., NCQ, Ultra DMA Out to 500 f (0° to 60° C) [case temp] Features ATA Security, S.M.A.R.T., NCQ, Ultra DMA Out to 500 f (0° to 60° C) [case temp] Features ATA Security, S.M.A.R.T., NCQ, Ultra DMA Out to 500 f (0° to 60° C) [case temp] Features ATA Security, S.M.A.R.T., NCQ, Ultra DMA Out to 500 f (0° to 60° C) [case temp] Features ATA Security, S.M.A.R.T., NCQ, Ultra DMA Operating Temperature 256 GB Height 0.09 in (2.23 mm) Width 0.87 in (22 mm) Interface ATA-8, SATA 3.0 Performance Maximum Sequential Maximum Sequential Write Read Interface ATA-8, SATA 3.0 Performance Dive 500,118,192 Operating Temperature 32° to 158°F (0° to 70°C) [Single Track	1.5 ms ~ 2 ms
Particle Participation Part			Average	12 ms ~13 ms
256 GB M2 2280 SATA-3 Rotational Speed 5400 rpm 256 GB M2 2280 SATA-3 Operating Temperature 32° to 140° F (0° to 60° C) [case temp] Features ATA Security, S.M.A.R.T., NCQ, Ultra DMA Self-Encrypting Drive (Opal 2) TLC Solid State Drive Drive Weight 0.02 lb (10 g) Keight 0.09 in (2.23 mm)		Setting/	Maximum	22 ms ~ 32 ms
Logical Blocks 976,773,168 Operating Temperature 32° to 140° F (0° to 60° C) [-ase temp] Features ATA Security, S.M.A.R.T., VCQ, Ultra DMA Self-Encrypting Drive (Opal 2) TLC Solid State Drive Weight 0.02 lb (10 g) Capacity 256 GB 22280 SATA-3 Nite Weight 0.02 lb (10 g)		Cache	Up to 128MB	
256 GB M2 2280 SATA-3 Self-Encrypting Drive (Opal 2) TLC Solid State Drive ATA Security, S.M.A.R.T., NCQ, Ultra DMA 256 GB M2 2280 SATA-3 Self-Encrypting Drive (Opal 2) TLC Solid State Drive Orive Weight 0.02 lb (10 g) Capacity 256 GB 222 mm) 256 GB Height 0.09 in (2.23 mm) Width 0.87 in (22 mm) Hiterface ATA-8, SATA 3.0 Height Maximum Sequential Read Maximum Sequential Maximus Sequential Performance Up to 530 MB/s Up to 515 MB/s Up to 515 MB/s Performance 2° co 158°F (0° to 70°C) [Rotational Speed	5400 rpm	
256 GB M2 2280 SATA-3 Self-Encrypting Drive (Opal 2) TLC Solid State Drive Drive Weight 0.02 lb (10 g) Capacity 256 GB 22.3 mm) Width 0.09 in (2.23 mm) Width 0.87 in (22 mm) Interface ATA-8, SATA 3.0 Performance Maximum Sequential Read Maximum Sequential Dive Interface No 0,118,192 Coperating Temperature Features 2° to 158°F (0° to 70°C)		Logical Blocks	976,773,168	
256 GB M2 2280 SATA-3 Self-Encrypting Drive (Opal 2) TLC Solid State DriveDrive Weight0.02 lb (10 g)4 Height256 GB		Operating Temperature	32° to 140° F (0° to 60° C) [case temp]
Self-Encrypting Drive (Opal 2) TLC Solid State Drive Capacity Capa		Features	ATA Security, S.M.A.R.T., N	CQ, Ultra DMA
(Opal 2) TLC Solid State DriveHeight0.09 in (2.23 mm)Width0.87 in (22 mm)InterfaceATA-8, SATA 3.0PerformanceMaximum Sequential ReadUp to 530 MB/sUp to 515 MB/sLogical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [==bient temp]FeaturesATA Security; TCG Opal 2 DIPM; TRIM; DEVSLPPrive Weight0.022 lb (10 g)Capacity512 GBHeight0.09 in (2.3 mm)Width0.87 in (22 mm)NAND TypeMLC		Drive Weight	0.02 lb (10 g)	
DriveHeight0.09 in (2.23 mm)Width0.87 in (22 mm)InterfaceATA-8, SATA 3.0PerformanceMaximum Sequential ReadMaximum Sequential Write ReadUp to 530 MB/sUp to 515 MB/sUp to 530 MB/sUp to 515 MB/sFogical Blocks500,118,192Operating Temperature Features32° to 158°F (0° to 70°C) [Capacity	256 GB	
InterfaceATA-8, SATA 3.0PerformanceMaximun Sequential ReadMaximun Sequential Sequential NemInterfaceNational Sequential Sequential DistabilityMaximun Sequential Sequencial Sequenci	-	Height		
PerformanceMaximum Sequential ReadMaximum Sequential Write ReadUp to 530 MB/sUp to 515 MB/sUp to 530 MB/sS00,118,192Soperating Temperature Features32° to 158°F (0° to 70°C) [0.87 in (22 mm)	
ReadUp to 530 MB/sUp to 515 MB/sUp to 530 MB/s500,118,192State DriveOperating Temperature Features32° to 158°F (0° to 70°C) [
Logical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesATA Security; TCG Opal 2.0, DIPM; TRIM; DEVSLPDrive Weight0.022 lb (10 g)Capacity512 GBHeight0.09 in (2.3 mm)Width0.87 in (22 mm)NAND TypeMLC		Performance	-	Maximum Sequential Write
HP Z Turbo Drive 512 GB M.2 NVMe MLC Solid State DriveOperating Temperature Features32° to 158°F (0° to 70°C) [ambient temp] ATA Security; TCG Opal 2.0, DIPM; TRIM; DEVSLPUrive Weight Capacity Height0.022 lb (10 g)Drive Weight Capacity Height0.09 in (2.3 mm)Width NAND Type0.87 in (22 mm)			Up to 530 MB/s	Up to 515 MB/s
HP Z Turbo Drive 512 GB, M.2 NVMe MLC Solid State DriveFeaturesATA Security; TCG Opal 2.0, DIPM; TRIM; DEVSLP0.022 lb (10 g)0.022 lb (10 g)Capacity512 GBHeight0.09 in (2.3 mm)Width0.87 in (22 mm)NAND TypeMLC		Logical Blocks	500,118,192	
HP Z Turbo Drive 512 GB, Drive Weight 0.022 lb (10 g) M.2 NVMe MLC Solid Capacity 512 GB State Drive Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) NAND Type MLC		Operating Temperature	32° to 158°F (0° to 70°C) [a	mbient temp]
M.2 NVMe MLC Solid Capacity 512 GB State Drive Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) NAND Type MLC		Features	ATA Security; TCG Opal 2.0,	, DIPM; TRIM; DEVSLP
State Drive Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) NAND Type MLC	-	Drive Weight	0.022 lb (10 g)	
Height0.09 in (2.3 mm)Width0.87 in (22 mm)NAND TypeMLC		Capacity	512 GB	
NAND Type MLC	State Drive	Height	0.09 in (2.3 mm)	
		Width	0.87 in (22 mm)	
Form-Factor (I/O) M.2 2280		NAND Type	MLC	
		Form-Factor (I/O)	M.2 2280	



Technical Specifications – Storage

	Interface	PCIe NVMe Gen3X4	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		Up to 3000 MB/s	Up to 1500MB/s
	Logical Blocks	1,000,215,216	
	Operating Temperature	32° to 158°F (0° to 70°C)	[ambient temp]
	Features	ATA Security (option), TR	RIM; L1.2
Turbo Drive 1 TB,	Drive Weight	0.02 lb (10 g)	
NVMe MLC Solid	Capacity	1024 GB	
te Drive	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	NAND Type	MLC	
	Form-Factor (I/O)	M.2 2280	
	Interface	PCIe NVMe Gen3X4	
	Drive Weight	0.02 lb (10 g)	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		Up to 3,000 MB/s	Up to 2,900 MB/s
	Logical Blocks	2,000,409,264	
	Operating Temperature	32° to 158°F (0° to 70°C)	[ambient temp]
	Features	ATA Security (Option),TR	IM; L1.2
Turbo Drive 256 GB,	Drive Weight	0.02 lb (10 g)	
2 NVMe MLC Solid Ite Drive	Capacity	256 GB	
	Height	0.09 in (2.23 mm)	
	Width	0.87 in (22 mm)	
	NAND Type	MLC	
	Form-Factor (I/O)	M.2 2280	
	Interface	PCIe NVMe Gen3X4	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		Up to 3,100 MB/s	Up to 1,400 MB/s
	Logical Blocks	500,118,192	
	Operating Temperature	32° to 158°F (0° to 70°C)	[ambient temp]
	Features	ATA Security (Option);TR	IM; L1.2

Technical Specifications – Storage

HP Z Turbo Drive 256 GB,	Drive Weight	0.02 lb (10 g)	
M.2 NVMe TLC Solid State Drive	capacity	256 GB	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	NAND Type	TLC	
	Form-Factor (I/O)	M.2 2280	
	Interface	PCIe NVMe Gen3X4	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		Up to 2,600 MB/s	Up to 900 MB/s
	Logical Blocks	500,118,192	
	Operating Temperature	32° to 158°F (0° to 70°C) [a	ambient temp]
	Features	ATA Security (Option); TRI	M; L1.2
HP Z Turbo Drive 512 GB,	Drive Weight	0.02 lb (10 g)	
M.2 NVMe TLC Opal 2 Solid State Drive	Capacity	512 GB	
Join Julie Drive	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	NAND Type	M.2 2280	
	Form-Factor (I/O)	PCIe NVMe Gen3X4	
	Interface	0.02 lb (10 g)	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		Up to 2,600 MB/s	Up to 1,400 MB/s
	Logical Blocks	1,000,215,216	
	Operating Temperature	32° to 158°F (0° to 70°C) [a	ambient temp]
	Features	ATA Security (Option);TRIM	1; L1.2
HP Z Turbo Drive 512 GB,		• • • · · · · ·	
M.2 SATA TLC FIPS Solid	-	0.02 lb (10 g)	
State Drive	Capacity	512 GB	
	Capacity Height	512 GB 0.09 in (2.3 mm)	
	Capacity Height Width	512 GB	
	Capacity Height Width Generation	512 GB 0.09 in (2.3 mm) 0.87 in (22 mm)	
	Capacity Height Width Generation NAND Type	512 GB 0.09 in (2.3 mm) 0.87 in (22 mm) TLC	
	Capacity Height Width Generation NAND Type Form-Factor (I/O)	512 GB 0.09 in (2.3 mm) 0.87 in (22 mm) TLC M.2 2280	
	Capacity Height Width Generation NAND Type Form-Factor (I/O) Interface	512 GB 0.09 in (2.3 mm) 0.87 in (22 mm) TLC M.2 2280 ACS-3, SATA 3.2	
	Capacity Height Width Generation NAND Type Form-Factor (I/O)	512 GB 0.09 in (2.3 mm) 0.87 in (22 mm) TLC M.2 2280 ACS-3, SATA 3.2 Maximum Sequential Read	Maximum Sequential Write
	Capacity Height Width Generation NAND Type Form-Factor (I/O) Interface Performance	512 GB 0.09 in (2.3 mm) 0.87 in (22 mm) TLC M.2 2280 ACS-3, SATA 3.2 Maximum Sequential Read Up to 530 MB/s	Maximum Sequential Write Up to 400 MB/s
	Capacity Height Width Generation NAND Type Form-Factor (I/O) Interface Performance	512 GB 0.09 in (2.3 mm) 0.87 in (22 mm) TLC M.2 2280 ACS-3, SATA 3.2 Maximum Sequential Read Up to 530 MB/s 1,000,215,216	Up to 400 MB/s
	Capacity Height Width Generation NAND Type Form-Factor (I/O) Interface Performance	512 GB 0.09 in (2.3 mm) 0.87 in (22 mm) TLC M.2 2280 ACS-3, SATA 3.2 Maximum Sequential Read Up to 530 MB/s 1,000,215,216 32° to 158°F (0° to 70°C) [a	Up to 400 MB/s



Technical Specifications – Storage

* For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to up to 30 GB (for Windows 10) disk is reserved for system recovery software.



Technical Specifications – Security

SECURITY

HP Fingerprint Sensor	Voltage	3.0-3.6V
	Operating temperature	14° - 167°F (-10° - 75°C)
	Current consumption image	36mA
	Low latency wait for finger	950 uA
	Capture rate	3000 lines/sec
	ESD Resistance	IEC 6100-4-2 4B (+/-15KV)
	Detection Matrix	200*1 (plus another secondary line); 508 dpi, sensor area 12*3 mm



Technical Specifications – Networking

NETWORKING/COMMUNICATION

Intel® I219-LM Gigabit Network Connection (vPro configurations)	Ethernet Features	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13- 14) 100 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 802.3 Clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE(Energy Efficient Ethernet) Jumbo Frame 9K Auto MDI/MDIX Crossover cable detection
	Power	ACPI compliant - multiple power modes
	Management Revformence	Energy Detect Low Power Mode(Green Ethernet)
	Performance Features	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload(ARP & NS) Large send offload and Giant send offload Receiving Side Scaling MACSec Offload (802.3ae) Intel® vPro iSCSI Boot RSS is kernel based support (e.g. in Win Server 2013) Ultra Low Power at cable disconnect (<1mW) enables platform support for connected standby.
	Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
	Interface	PCI Express 1.1 x1 to fully support ASPM LOs/L1 and CLKREQ. NOTE: Intel [®] I219-LM Gigabit interface is not PCIe compliant. It operates at half of PCIe specification V1.1 (2.5GT/S) speed.
	NIC Device Driver Name	Intel [®] Ethernet Network Connection I219-LM

Intel® 1219-V Gigabit Network Connection (Non-vPro configurations)	Ethernet Features	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023. Clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE(Energy Efficient Ethernet) Jumbo Frame 9K Auto MDI/MDIX Crossover cable detection
	Power Management	ACPI compliant - multiple power modes Energy Detect Low Power Mode(Green Ethernet)
	Performance Features	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload(ARP & NS) Large send offload and Giant send offload Receiving Side Scaling MACSec Offload (802.3ae) Intel Non-vPro iSCSI Boot
	Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
	Interface	PCI Express 1.1 x1 to fully support ASPM LOs/L1 and CLKREQ. NOTE: Intel® 82579 PCIe interface is not PCIe compliant. It operates at half of PCIe specification V1.1 (2.5GT/S) speed.
	NIC Device Driver Name	Intel [®] 82579LM/82579V Ethernet Network Connection



HP lt4132 LTE/HSPA+ 4G Mobile Broadband Module

Technology/Operating bands	LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3) MHz, 850 (Band 5), 2600 (Band 7), 900 (Band 8) MHz, 800 (Band 20), 700 (Band 28) MHz. HSPA+: 2100 (Band 1), 1900 (Band 2), 850 (Band 5), 900 (Band 8) MHz E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 900 (Band 8) MHz
Wireless protocol standards	3GPP Release 10 LTE Specification CAT.4, 20MHz BW WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification E-GPRS: Class B, Multi-slot class 12, coding schemes CS1 - CS4 and MSC1 - MSC9
GPS	Standalone, A-GPS (MS-B and LTO)
GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz
Maximum data rates	LTE: 150 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload) EDGE: 236.8 kbps (Download), 236.8 kbps (Upload) GPRS: 85.6 kbps(Download), 85.6 kbps (Upload)
Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm E-GPRS 1900/1800: 26 dBm E-GPRS 900/850: 27 dBm GPRS 1900/1800: 29.5 dBm GPRS 900/850: 32.5 dBm
Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average) E-GPRS: 2,600 mA (peak); 500 mA (average)
Form Factor	M.2, 3042-S3 Key B
Weight	6 g
Dimensions (Length x Width x Thickness)	42 x 30 x 2.3 mm

* Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

HP hs3210 HSPA+ Mobile Broadband Module*

Technology/Operating bands	HSPA+: 2100 (Band1), 1900 (Band 2), 850 (Band 5), 900 (Band 8) MHz E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 MHz (Band 5), 900 (Band 8) MHz
Wireless protocol standards	WCDMA R99, 3GPP Release 5, 6 and 7 UMTS Specification E-GPRS: Class B, Multi-slot class 33, coding schemes CS1 - CS4 and MSC1 - MSC9
Maximum data rates	HSPA+: 21.6 Mbps (Download), 5.76 Mbps (Upload)
	E-GPRS: 296 kbps (Download), 236.8 kbps (Upload) GPRS: 107 kbps (Download), 85.6 kbps (Upload)
Maximum output power	HSPA+: 24 dBm E-GPRS 1800/1900: 26 dBm E-GPRS 850/900: 27 dBm



	GPRS 1800/1900: 30 dBm GPRS 850/900: 33 dBm
Maximum power consumption	HSPA+: 1,100 mA (peak); 800 mA (average) E-GPRS: 2,800 mA (peak); 700 mA (average)
Form Factor	M.2, 2242-S3 Key B
Weight	6 g
Dimensions (Length x Width x Thickness)	1.65 x 8.66 x 0.09 in (42 x 22 x 2.38 mm)

* Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors.

HP lt4120 Qualcomm[®] Snapdragon™ X5 LTE Mobile Broadband Module

Technology/Operating bands	LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 800 (Band 20), 700 (Band 28). HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8) MHz EV-D0: 850 (BC0), 1900 (BC1) MHz (Only work with Verizon network) E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 900 (Band 8) MHz
Wireless protocol standards	3GPP Release 10 LTE Specification CAT.4, 20MHz BW WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification 1xEVDO Release 0, A and B. E-GPRS: Class B, Multi-slot class 12, coding schemes CS1 - CS4 and MSC1 - MSC9
GPS	Standalone, A-GPS (MS-A, MS-B and XTRA)
GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz
Maximum data rates	LTE: 150 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload) CDMA 1xRTT: 153.6 kbps (Download), 153.6 kbps (Upload) EVDO Rel.A: 3.1 Mbps (Download), 1.8 Mbps (Upload) EVDO Rel.B: 14.7 Mbps (Download), 5.4Mbps (Upload) EDGE: 236.8 kbps (Download), 236.8 kbps (Upload) GPRS: 85.6 kbps(Download), 85.6 kbps (Upload)
Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm 1xRTT/EVDO: 24dBm E-GPRS 1900/1800: 26 dBm E-GPRS 900/850: 27 dBm GPRS 1900/1800: 29.5 dBm GPRS 900/850: 32.5 dBm
Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average) 1xRTT/EVDO: 1,000 mA (peak); 700 mA (average) E-GPRS: 2,800 mA (peak); 500 mA (average)
Form Factor	М.2, 3042-S3 Кеу В
Weight	6.2 g



Technical Specifications – Networking

Dimensions42 x 30 x 2.3 mm(Length x Width xThickness)

Intel® Dual Band Wireless-AC 8265 802.11 AC/a/b/g/n (2x2) WiFi + Bluetooth® 4.2 Combo Adaptor* (vPro)		IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11n	
	Interoperability	Wi-Fi certified	
	Frequency Band	802.11b/g/n	2.402 - 2.482 GHz Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels
		802.11a	4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz Note: Indonesia only supports 5.725 - 5.825 GHz (CH149 - CH161)
	Data Rates	 802.11b: 1, 2, 2 802.11g: 6, 9, 2 802.11n: MCS 0 	12, 18, 24, 36, 48, 54 Mbps 5.5, 11 Mbps 12, 18, 24, 36, 48, 54 Mbps 0 ~ MCS 15, (20MHz, and 40MHz) 50 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and
	Modulation	Direct Sequence Sprea CCK, BPSK, QPSK, 16-C	d Spectrum AM, 64-QAM, 256-QAM
	Security ¹	 IEEE and Wi-Fi compliant 64 / 128 bit WEP encryption fo a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AE WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI 	
	Network Architecture	Ad-hoc (Peer to Peer)	
	Models	Infrastructure (Access	-
	Roaming	•	roaming between band Access Points
	Output Power ²	 802.11g:+14 802.11a:+14 802.11n HT20 	5dBm minimum 9dBm minimum 9dBm minimum 0(2.4GHz) : +13dBm minimum 0(2.4GHz) : +13dBm minimum



Technical Specifications – Networking

		T20(5GHz) : +12dBm minimum T40(5GHz) : +12dBm minimum	
Power Consumption	 802.11n HT40(5GHz) : +12dBm minimum Transmit: 2.0 Watts (max) Receive: 1.6 Watts (max) Idle mode (PSP): 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connect Standby: 10mW (WLAN + BT) Radio disabled: 5 mW 		
Power Management	ACPI and PCI Expres 802.11 compliant p	s compliant power management ower saving mode	
Receiver Sensitivity ³	802.11b, 1Mbps : -94dBm maximum 802.11b, 11Mbps : -86dBm maximum 802.11g, 6Mbps : -88dBm maximum 802.11g, 54Mbps : -74dBm maximum 802.11a, 6Mbps : -88dBm maximum 802.11a, 54Mbps : -74dBm maximum 802.11n, MCS07 : -69dBm maximum 802.11n, MCS15 : -66dBm maximum 802.11ac, 1SS, MCS-0 : -86dBm maximum 802.11ac, 2SS, MCS-0 : -83dBm maximum 802.11ac, 2SS, MCS-9 : -58dBm maximum		
Antenna Type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO and Bluetooth communications		
Form Factor	PCI-Express M.2 MiniCard		
Dimensions	Type 2230 : 2.3 x 22 Or Type 1630 : 2.3 x 16		
Weight	Type 2230 : 2.8g Or Type 1630 : 2g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating Non-operating	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)	
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)	
Altitude	Operating Non- operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio	OFF; LED White – Radio ON	

Technical Specifications – Networking

HP Integrated Module with Bluetooth®	Bluetooth® Specification	4.2 Compliant			
4.2 Wireless Technology	Frequency Band	2402 to 2480 MH	łz		
	Number of Available Channels	Legacy: 0~79 (1 BLE: 0~39 (2 MH;			
	Data Rates and Throughput	Legacy: 3 Mbps d	lata rate; throug	ghput up to 2.1	7 Mbps
		BLE: 1 Mbps data	rate; throughp	ut up to 0.2 Mb	ps
		Legacy: Synchron voice channels	nous Connectio	n Oriented links	s up to 3, 64 kbps,
		Legacy: Asynchro kbps asymmetric			178.1 kbps/177.1 ric (3-EV5)
	Transmit Power	The Bluetooth co device with a ma	•	•	ass II Bluetooth IBm for BR and EDR
	Receiver Sensitivity	Modulation	0.01% BER	0.001% BER]
		GFSK	-80 dBm	-70 dBm	
		π/4-DQPSK	-80 dBm	-70 dBm	
		8DPSK	-80 dBm	-70 dBm	
	Power Consumption	Peak (Tx) 330 m Peak (Rx) 230 m Selective Suspen	W		
	Antenna	Internally integra	ated within mod	lule	
	Range	Legacy Up to 33 BLE Up to 99 ft (3			
	Electrical Interface	USB 2.0 complia	nt		
	Bluetooth® Software Supported	Microsoft Windo	ws Bluetooth Sc	oftware	
	Link Topology	Point to Point, M	ultipoint Pico N	ets up to 7 slav	es
	Security	Full support of B	luetooth Securi	ty Provisions	
	Power Management Certifications	Microsoft Windo	ws ACPI, and US	B Bus Support	
		Self-configurable modes, including			ion in all operating f
	Security	All necessary reg including:	Julatory approv	als for support	ed countries,
		FCC (47 CFR) Part	t 15C, Section 1	5.247 & 15.249	Э
	Power management certificactions	ETS 300 328, ETS Low Voltage Dire UL, CSA, and CE N	ctive IEC950		
	Certifications Bluetooth® Profiles Supported	Serial Port Profil Service Discover Dial-Up Network Generic Object Ex Object Push Prof Hard Copy Cable Personal Area Ne Human Interface Hands Free Profi Advanced Audio Audio Video Rem	y Application Pr ing (DUN)1,2 kchange Profile ile (OPP)1,2 Replacement (H tworking Profil Device Profile (le (HFP) Distribution Pro	(GOEP)1,2 ICRP)1,2 e (PAN)1,2 HID)1,2 file (A2DP)	



Bluetooth® V4.2 support feature

V4.2: ESR8 compliant, LE Secure Connection – Basic.

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CCK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

WLAN supplier's client utility is required for Cisco Compatible Extensions support with Microsoft Windows XP. WLAN may also be compatible with certain third-party software supplicants. WLAN supplier IHV extensions required for Cisco Compatible Extensions support for Microsoft Windows Vista.



hp

Technical Specifications – Networking

Intel® Dual Band Wireless-AC 8265 802.11 AC/a/b/g/n (2x2) WiFi + Bluetooth® 4.2 Combo Adaptor* (non-vPro)	Wireless LAN Standards Interoperability Frequency Band	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac Wi-Fi certified 802.11b/g/n
		2.402 - 2.482 GHz Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels
		 802.11a 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz Note: Indonesia only supports 5.725 - 5.825 GHz (CH149 - CH161)
	Antenna Structure Data Rates	2 transmit; 2 receive (2x2) 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: card will support rates for NSS=1 and NSS=2 for RX and TX for 20 and 40 MHz channels. Short and long guard interval shall be supported. 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
	Modulation Security ¹	 Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM IEEE and Wi-Fi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI
	Network Architecture Models Roaming Output Power ²	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b : +16dBm minimum • 802.11g : +14dBm minimum • 802.11a : +14dBm minimum



	 802.11n H1 802.11n H1 802.11n H1 	T2O(2.4GHz) : +13dBm minimum T4O(2.4GHz) : +13dBm minimum T2O(5GHz) : +12dBm minimum T4O(5GHz) : +12dBm minimum OMHz(5GHz) : +11dBm minimum	
Power Consumption	Transmit: 2.0 W (ma Receive: 1.6 W (max Idle mode (PSP): 180 Idle mode: 60 mW (\ Radio disabled: 30 n) 0 mW (WLAN Associated) VLAN unassociated)	
Power Management	ACPI and PCI Expres 802.11 compliant po	s compliant power management ower saving mode	
Receiver Sensitivity ³	802.11g:-90 dBm (6 Mbps), -89 dBm (9 Mbps), -87 dBm (12 Mbps), - 85 dBm (18 Mbps), -82 dBm (24 Mbps), -79 dBm (36 Mbps), -76 dBm (48 Mbps), -74 dBm (54 Mbps)		
	802.11b:-95 dBm (1 88 dBm (11 Mbps)	Mbps), -93 dBm (2 Mbps), -91 dBm (5.5 Mbps), -	
		Mbps), -89 dBm (9 Mbps), -87 dBm (12 Mbps), - 82 dBm (24 Mbps), -79 dBm (36 Mbps), -76 dBm (54 Mbps)	
	802.11n:-69 dBm (1	50 Mbps), -66 dBm (300 Mbps)	
Antenna type	display enclosure Two embedded dua	nna with spatial diversity, mounted in the l band 2.4/5 GHz antennas are provided to the N MIMO communications and Bluetooth	
Form Factor	PCI-Express Half-MiniCard		
Dimensions	0.134 x 1.06 x 1.18 in (3.4 x 26.8 x 30 mm)		
Weight	3.1g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating Non-operating	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)	
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)	
Altitude	Operating Non-operating	0 to 10,000 ft. (3,048 m) 0 to 50,000 ft. (15,240 m)	
LED Activity	LED Amber - Radio (0FF; LED White - Radio ON	
1 Check latest software/driver re	ease for undates on sum	norted security features	

1. Check latest software/driver release for updates on supported security features.

2. Maximum output power may vary by country according to local regulations.

3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth® 4.2 Wireless Technology

Bluetooth Specification	4.0+EDR Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	79 (1 MHz) available channels
Data Rates and Throughput	3 Mbps data rate; throughput up to 2.17 Mbps



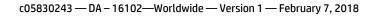
Technical Specifications – Networking

5	
	Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric or 1306.9 kbps symmetric
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of +4 dBm for BR and EDR
Receiver Sensitivity	Better than -20 dBM at 0.1 % raw bit error rate
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Antenna	Internally integrated within module
Range	Up to 33 ft. (10 m)
Electrical Interface	USB 2.0 compliant
	Microsoft Windows Plug and Play compliant
Bluetooth [®] Software	Broadcom Bluetooth for Windows
Supported	Microsoft Windows Bluetooth Software
Link Topology	Point to Point, Multipoint Pico Nets up to 7 slaves
Security	Full support of Bluetooth Security Provisions
Power Management	Microsoft Windows ACPI, and USB Bus Support
	Self-configurable to optimize power conservation in all operating modes, including Standby, Hold, Park, and Sniff
Certifications	All necessary regulatory approvals for supported countries, including:
	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
	ETS 300 328, ETS 300 826
	Low Voltage Directive IEC950
	UL, CSA, and CE Mark
Bluetooth® Profiles Supporter	 Serial Port Profile (SPP)¹ Service Discovery Application Profile (SDAP) Dial-Up Networking (DUN)^{1,2} Generic Object Exchange Profile (GOEP)^{1,2} Object Push Profile (OPP)^{1,2} File Transfer Profile (FTP) Synchronization Profile (SYNC) Hard Copy Cable Replacement (HCRP)^{1,2} Personal Area Networking Profile (PAN)^{1,2} Human Interface Device Profile (HID)^{1,2} FAX Profile (FAX) Basic Imaging Profile (BIP)² Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)
2. Indicates the profile is part o	orted by Microsoft Windows XP SP2 f Windows Vista ernet service required. Availability of public wireless access points



Technical Specifications – Networking

Intel® Dual Band Wireless- AC 3168 802.11 ac (1x1) WiFi and Bluetooth® 4.2 Combo Adapter (non-vPro)	Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac Wi-Fi certified 802.11b/g/n • 2.402 – 2.482 GHz		
		Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.		
		802.11a/n • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz		
	Data Rates	 Note: Indonesia only supports 5.725 - 5.825 GHz (CH149 - CH161) 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac : MCS0 ~ MCS7, (1SS) (20MHz, 40MHz, and 80MHz) 		
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM		
	Security ¹	 IEEE and Wi-Fi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI 		
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)		
	Roaming	IEEE 802.11 compliant roaming between access points		
	Output Power ²	 802.11b : +16dBm minimum 802.11g : +14dBm minimum 802.11a : +14dBm minimum 802.11a : +14dBm minimum 802.11n HT20(2.4GHz) : +13dBm minimum 802.11n HT40(2.4GHz) : +13dBm minimum 802.11n HT20(5GHz) : +12dBm minimum 802.11n HT40(5GHz) : +12dBm minimum 802.11ac 80MHz(5GHz) : +11dBm minimum 		
	Power Consumption	Transmit: 2.0 W (max)		





Technical Specifications – Networking

			180 mW (WLAN Associated) mW (WLAN unassociated)
		Radio disabled: 3	
	Power Management	•	ess compliant power management power saving mode
	Receiver Sensitivity ³	•	-94dBm maximum
		· · ·	: -86dBm maximum
		- · · · ·	-88dBm maximum : -74dBm maximum
		- · · ·	-86dBm maximum
		802.11a, 54Mbps	: -72dBm maximum
			-69dBm maximum
			-66dBm maximum CS-0 : -86dBm maximum
			CS-9 : -61dBm maximum
			CS-0: -83dBm maximum
			CS-9 : -58dBm maximum
	Antenna type	enclosure	tenna with spatial diversity, mounted in the display
			ual band 2.4/5 GHz antennas are provided to the card to
		support WLAN MI	MO communications and Bluetooth communications
	Form Factor	PCI-Express M.2 M	1iniCard
	Dimensions	Type 2230 : 2.3 x Or	22.0 x 30.0 mm
		Туре 1630 : 2.3 х	16.0 x 30.0 mm
	Weight	Type 2230 : 2.8g	
		Or Type 1630 : 2g	
	Operating Voltage	3.3v +/- 9%	
	Temperature	Operating	14° to 158° F (-10° to 70° C)
		Non-operating	40° to 176° F (-40° to 80° C)
	Humidity	Operating	10% to 90% (non-condensing)
		Non-operating	5% to 95% (non-condensing)
	Altitude	Operating	0 to 10,000 ft (3,048 m)
		Non-operating	0 to 50,000 ft (15,240 m)
Near Field Communication	s (NFC)		
	Controller	HP Module with N	XP NFC Controller NPC100
	Supports		8, Proximity Events
			57, PC/SC
			m Compliant
		Near Fiel	d Communications Controller
	Dimensions	Module 25 mm by	y 10 mm by 2.0 mm
	(L x W x H)	. Iouale L9 mill by	,
	Chipset	NPC100	
	System interface	12C	
	NFC RF standards		14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 1 Target and Initiator ECMA-320 NFCIP-2



Technical Specifications – Networking

NFC Forum Support Tag	Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2		
Reader	(PCD-VCD) Mode(1) ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Jewel and Topaz cards		
Card Emulation	(PICC-VICC)		
Mode ¹	ISO/IEC 14443 A ISO)/IEC 14443 B and B' MIFARE FeliCa	
Frequency	13.56 MHz		
NFC Modes Supported	Reader/Writer, Pee	r-to-Peer	
Raw RF Data Rates	106, 212, 424, 848	kbps	
Operating temperature	0°C to 70°C		
Storage temperature	-20°C to 125°C		
Humidity	10-90% operating	5-95% non-operating	
Supply Operating voltage	2.97 to 5.5 Volts		
I/O Voltage	1.8V or 3.3V		
Power Consumption	Booster enable,	VBAT= 3.3V,	
	VCC_BOOST = 5V) Mode Power Consumption,	Typical ² Polling 7.3 mA Detected Test Tag Type 1 Total 283.8 mA Net Module 236.8 mA Detected Test Tag Type 2 Total 288.8 mA Net Module 241.8 mA Detected Test Tag Type 3 Total 287.7 mA Net Module 240.7 mA Detected Test Tag Type 4 Total 282.3 mA Net Module 235.3 mA	
Antenna connector	0.5mm pitch, 7 con	nector FPC. Antenna matching is external to module.	
Notes	2. Actual Pov	cation or UICC support ver Consumption is dependent on NFC antenna and circuit and on the particular polling sequence and period I.	



Technical Specifications – Audio

AUDIO/MULTIMEDIA – BANG & OLUFSEN

Hardware	Implementation Function Key Volume Controls	Conexant CX7501 Volume up, volume down, and mute
	Line In/Line Out	Yes, via dock
	Headphone/Microphone in	Yes combo jack
	Integrated Microphone	Yes, dual digital microphone array when equipped with optional webcam
Audio Output Quality	Frequency Response	20 Hz - 20 kHz
	Signal to Noise Ratio	>85 dB
	Total Harmonic Distortion	0.01%
	Noise Floor	-110 dB
	Play/Record Sampling Rate	s) 8 kHz – 48kHz
	DAC	16, 20 or 24-bit
	ADC	16,20-bit
Integrated Stereo	Power Rating	2 Watts
Speakers	Impedance	4 Ohms

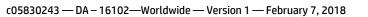


Technical Specifications – Power

POWER

HP 65W Smart AC Adapter Dimensions 107.0x47.0x30.0mm Weight unit: 250g +/-10g Input Input 90 to 265 VAC Issue and 89.0% at 230 Vac Input Ffficiency 88.0% at 115 Vac and 89.0% at 230 Vac Input Ffficiency 47 to 63 Hz range 100 tutput power Output 0utput power Output 9.0% to 215 VAC Hold-up time 5 ms at 115 Vac input Output 9.0% to 25° F (0° to 35° C) KC connector (Ac Inlet) Operating (storage) -4° to 185° F (0° to 35° C) Environmental Design 100 to 16,400 ft (0 to 5,000 m) Humidity Humidity 20% to 95% Storage Humidity 10% to 95% EMI and Safety Certifications *CE Mark - full compliance with LVD and EMC directives *Worldwide safety standards - IEC60950, EM60950, UL60950, Class SCLV, Agency approvals - C-U-US, NORDICS, DENAN, EM55022 Class FCC Class B, CSPR22 Class B, CSC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition. MTBF - over 200,000 hours at 25°C ambient condition. MP 65W Smart AC Adapter EM Dimensions 102.0x55.0x30.0mm Weight unit: 350g +/- 10g Input Efficiency NP 00 to				
 Weight Unit: 250 9'7' 109 Input 90 to 265 VAC Input Frequency 47 to 63 Hz range Input AC current 1.7 A at 90 Vac Output Output Output DC output DC outpu	HP 65W Smart AC	Dimensions	107.0x47.0x30.0mm	
Input Efficiency 88.0 % at 115 Vac and 89.0 % at 230 Vac Input frequency 47 to 63 Hz Input AC current 1.7 A at 90 Vac Output Output power 65W Dc output power AC connector (Ac Inlet) Sm sat 115 Vac input AC connector (Ac Inlet) Operating (storage) -4" to 185" F (-20" to 85" C) Environmental Design Temperature 32" to 95" F (0" to 35" C) Non-operating (storage) -4" to 185" F (-20" to 85" C) EMI and Safety Certifications *CE Mark - full compliance with UD and EMC directives * Worldwide safety standards - IECOS90, ENSOS0, UL60950, Class SELV; Agency approvals - C-UL-US, NORDICS, DENAN, ENSO22 Class FEC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25" C ambient condition. HP 65W Smart & Weight 102.0x55.0x30.0mm Weight unit: 350g +/ 10g Input Efficiency 87.0% min at 115 VAC and 230Vac Input frequency 47 to 63 Hz range Input Efficiency 90 to 255 VAC Input frequency Input frequency 47 to 63 Hz range Input frequency 47 to 63 Hz Input 90 to 255 VAC Input fre	Adapter	Weight	unit: 250g +/- 10g	
Input frequency range 47 to 63 Hz Input AC current 1.7 A at 90 Vac Output 65W DC output 19.5V Hold-up time 5 ms at 115 Vac input Output current limit <11.0A AC Connector (Ac Inlet) C6 (3pin/with grounded, with Smart ID DC connector) AC Connector (Ac Inlet) Operating temperature 32° to 95° F (0° to 35° C) AC Connector (Ac Inlet) Operating temperature 32° to 95° F (0° to 35° C) Non-operating (storage) -4° to 185° F (-20° to 85° C) -4° to 185° F (-20° to 85° C) EMI and Safety Certifications *CE Mark - full compliance with LO and EMC directives * Worldwide safety standards - IEC60950, EM60950, UL60950, Class SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class FCC C Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,OU Oburs at 25°C ambient condition. PF 65W Simart AC Adapter EM Dimensions 102.0x55.0x30.0mm Weight unit: 350g +/- 10g - Input Fficiency 87.0% min at 115 VAC and 230Vac Input AC current 1.7 A at 90 VAC Output power 65W Doutput power 65W		Input	90 to 265 VAC	
MP 65W Smart AC Adapter EM Dimensions 102.0x55.0x30.0mm Weight unit: 350g +/- 10g min at 115 VAC and 230Vac Input Efficiency 87.0% min at 115 VAC and 230Vac Input Efficiency 47 to 63 Hz Input AC current 1.7 A at 90 VAC Output Output power 65W Display Display 65W Display Display 1.7 A at 90 VAC Dutput Display 1.7 A at 90 VAC			Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230 Vac
Mutput power 65W DC output 19.5V Hold-up time 5 ms at 115 Vac input Output current limit <11.0A AC Connector (Ac Inlet) C6 (3pin/with grounded, with Smart ID DC connector) AC Connector (Ac Inlet) C6 (3pin/with grounded, with Smart ID DC connector) AC Connector (Ac Inlet) Operating Burnon 32° to 95° F (0° to 35° C) Innon-operating (storage) (storage) -4° to 185° F (-20° to 85° C) Innon-operating (storage) (storage) -4° to 185° F (-20° to 85° C) Innuidity 20% to 95% EMI and Safety Certifications *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards = IEC60950, ENSOP50, UL60950, Class \$SELV, Agency approvals - C-UL-US, NORDICS, DENAN, ENSO22 Class FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 + burs at 25°C ambient condition. HP 65W Smart Dimensions 102.0x55.0x30.0mm Meight unit: 350g +/- 10g Input frequency Input frequency 47 to 63 Hz range Input frequency 47 to 63 Hz range Input AC current 1.7 A				47 to 63 Hz
HP 65W Smart AC Adapter EM Dimensions 102.0x55.0x30.0mm			Input AC current	1.7 A at 90 Vac
Hold-up time 5 ms at 115 Vac input AC Connector (Ac Inlet) C6 (3pin/with groundeedwith Smart ID DC connector) AC Connector (Ac Inlet) Operating temperature 32° to 95° F (0° to 35° C) Non-operating (storage) -4° to 185° F (-20° to 85° C) Itemperature Attitude 0 to 16,400 ft (0 to 5,000 m) Humidity 20% to 95% EMI and Safety Certifications *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EIK0950, UL60950, Class SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class FCC Class B, CSPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition. * MTBF - over 200,000 hours at 25°C ambient condition. MP 65W Smart AC Adapter EM Dimensions 102.0x55.0x30.0mm Weight unit: 350g +/- 10g Input Efficiency Input frequency 47 to 63 Hz range Input AC current 1.7 A at 90 VAC Output Output power 65W Didupt frequency 65W		Output	Output power	65W
AC Connector (Ac Inlet) C6 (3pin/with grounded, with Smart ID DC connector) AC Connector (Ac Inlet) Operating temperature 32° to 95° F (0° to 35° C) Non-operating (storage) -4° to 185° F (-20° to 85° C) temperature Altitude 0 to 16,400 ft (0 to 5,000 m) Humidity 20% to 95% EMI and Safety Certifications *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN5502 Class SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN5502 Class SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN5502 Class SELV; Agency approvals -			DC output	19.5V
AC Connector (Ac Inlet) C6 (3pin/with grounded, with Smart ID DC connector) AC Connector (Ac Inlet) Operating temperature 32° to 95° F (0° to 35° C) Non-operating (storage) -4° to 185° F (-20° to 85° C) temperature Altitude 0 to 16,400 ft (0 to 5,000 m) Humidity 20% to 95% Storage Humidity 10% to 95% EMI and Safety Certifications *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN5502 Class SELV; Agency			Hold-up time	5 ms at 115 Vac input
AC Connector (Ac Inlet) Environmental Design Operating temperature (storage) 32° to 95° F (0° to 35° C) Non-operating (storage) -4° to 185° F (-20° to 85° C) temperature Altitude 0 to 16,400 ft (0 to 5,000 m) Humidity 20% to 95% Storage Humidity 10% to 95% EMI and Safety Certifications *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition. HP 65W Smart AC Adapter EM Dimensions 102.0x55.0x30.0mm Weight unit: 350g +/- 10g Input Efficiency Input Efficiency 87.0% min at 115 VAC and 230Vac Input frequency range 47 to 63 Hz Input AC current 1.7 A at 90 VAC Output Output power 65W DC output 19.5V			Output current limit	<11.0A
Environmental Design temperature 32° to 95° F (0° to 35° C) Non-operating (storage) -4° to 185° F (-20° to 85° C) temperature Altitude 0 to 16,400 ft (0 to 5,000 m) Humidity 20% to 95% EMI and Safety Certifications *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition. HP 65W Smart AC Adapter EM Dimensions 102.0x55.0x30.0mm Weight unit: 350g +/- 10g Input 90 to 265 VAC Input Efficiency 87.0% min at 115 VAC and 230Vac Input frequency range 47 to 63 Hz Output Output power 65W DC output 19.5V		AC Connector (Ac Inlet)	C6 (3pin/with grounde	ed, with Smart ID DC connector)
HP 65W Smart AC Adapter EM Dimensions 102.0x55.0x30.0mm Weight Input 00 to 265 VAC Input Efficiency 87.0% min at 115 VAC and 230Vac Input frequency range 107 to 63 Hz range Output 00 to 10,400 ft (0 to 5,000 m) HP 65W Smart AC Adapter EM 0 to 16,400 ft (0 to 5,000 m) HP 65W Smart AC Adapter EM Dimensions 102.0x55.0x30.0mm Verificiency 87.0% min at 115 VAC and 230Vac Input 200 to 65 VAC Input 200 to 65 V				32° to 95° F (0° to 35° C)
Humidity 20% to 95% Storage Humidity 10% to 95% EMI and Safety Certifications *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition. HP 65W Smart Dimensions 102.0x55.0x30.0mm AC Adapter EM Weight unit: 350g +/- 10g Input 90 to 265 VAC Input Efficiency Input frequency 47 to 63 Hz range Input AC current 1.7 A at 90 VAC Output Output power 65W DC output 19.5V 19.5V			(storage)	-4° to 185° F (-20° to 85° C)
Kendenkin 10% to 95% EMI and Safety Certifications *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class SELV: Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition. HP 65W Smart AC Adapter EM Dimensions 102.0x55.0x30.0mm Weight Input unit: 350g +/- 10g minut: 350g +/- 10g Input Efficiency 87.0% min at 115 VAC and 230Vac Input frequency range 47 to 63 Hz Input AC current 1.7 A at 90 VAC Output Output power 65W DC output 19.5V			Altitude	0 to 16,400 ft (0 to 5,000 m)
EMI and Safety Certifications *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition. HP 65W Smart AC Adapter EM Dimensions 102.0x55.0x30.0mm Weight unit: 350g +/- 10g Input 90 to 265 VAC Input Efficiency 87.0% min at 115 VAC and 230Vac Input frequency 47 to 63 Hz range Input AC current 1.7 A at 90 VAC Output Output power 65W DC output 19.5V			Humidity	20% to 95%
* Worldwide safety standards - IEC60950, EN60950, UL60950, Class SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition. HP 65W Smart Dimensions 102.0x55.0x30.0mm Weight unit: 350g +/- 10g Input 90 to 265 VAC Input Efficiency 87.0% min at 115 VAC and 230Vac Input frequency 47 to 63 Hz range Input AC current 1.7 A at 90 VAC Output Output power 65W DC output 19.5V			Storage Humidity	10% to 95%
AC Adapter EM Weight unit: 350g +/- 10g Input 90 to 265 VAC Input Efficiency 87.0% min at 115 VAC and 230Vac Input frequency 47 to 63 Hz range Input AC current 1.7 A at 90 VAC Output 0utput power 65W DC output 19.5V		EMI and Safety Certifications	* Worldwide safety sta SELV; Agency approva FCC Class B, CISPR22 C	andards - IEC60950, EN60950, UL60950, Class1, Ils - C-UL-US, NORDICS, DENAN, EN55022 Class B, Class B, CCC, NOM-1 NYCE.
Input90 to 265 VACInput Efficiency87.0% min at 115 VAC and 230VacInput frequency range47 to 63 HzOutputInput AC current1.7 A at 90 VACOutputOutput power65WDC output19.5V			102.0x55.0x30.0mm	
Input Efficiency87.0% min at 115 VAC and 230VacInput frequency range47 to 63 HzInput AC current1.7 A at 90 VACOutputOutput powerDC output19.5V	AL Adapter EM	Weight	unit: 350g +/- 10g	
Input frequency range47 to 63 HzInput AC current1.7 A at 90 VACOutputOutput powerDC output19.5V		Input		
range Input AC current 1.7 A at 90 VAC Output Output power 65W DC output 19.5V			• •	
OutputOutput power65WDC output19.5V				47 to 63 Hz
DC output 19.5V			Input AC current	1.7 A at 90 VAC
•		Output	Output power	65W
Hold-up time 5 ms at 115 Vac input			DC output	19.5V
			Hold-up time	5 ms at 115 Vac input

AC Connector (Ac Inlet)



Output current limit <11.0A

C6 (3pin/with grounded, with Smart ID DC connector)



Technical Specifications – Power

AC Connector (Ac Inlet) Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
	Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
	Altitude	0 to 16,400 ft (0 to 5,000 m)
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
EMI and Safety Certifications	 *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition. 	

HP 65W Travel	Dimensions	120.0x57.6x16.7mm	
AC Adapter	Weight	unit: 250g +/- 10g	
	Input	Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230Vac
		Input frequency range	47 to 63 Hz
		Input AC current	1.7 A at 90 Vac
	Output	Output power	65W
		DC output	19.5V/5V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<11.0A
	DC Plug	4.5mm/7.4mm tips	
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	*CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.	

Technical Specifications – Power

HP Long Life 3-cell	Dimensions (H x W x L)	6.8mm x 102.8mm x 198n	ım
Polymer Battery (51WHr)	Weight	235 g	
	Cells/Type	3cell Lithium-Ion Polymer	cell / 506480
	Energy	Voltage	11.55V
		Amp-hour capacity	4420mAh
		Watt-hour capacity	51wh
	Temperature	Operating (Charging)	32° to 113° F (0° to 45° C)
		Operating (Discharging)	14° to 140° F(-10° to 60° C)
	Fuel Gauge LED	No	
	Warranty	1000 cycles > 65% (at 23°	C)
	Optional Travel Battery Available	No	



Technical Specifications – Environmental

ENVIRONMENTAL DATA

Eco-Label Certifications & declarations	 This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR[®] EPEAT <gold> registered in the United States. See http://www.epeat.net for registration status in your country.</gold> The configuration used for the Energy Consumption and Declared Noise Emissions data for the 		
System Configuration	Notebook model is based on a "Ty		
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	9.06 W	9.98 W	9.6 W
Normal Operation (Long idle)	7.31 W	7.82 W	8.0 W
	0.76 W	0.89 W	0.75 W
Sleep			
Off	0.44 W	0.56 W	0.43 W
	NOTE: Energy efficiency data listed is for family. HP computers marked wit U.S. Environmental Protection Ag model family does not offer ENER data listed is for a typically config supply, and a Microsoft Windows ⁶	h the ENERGY STAR [®] Logo a ency (EPA) ENERGY STAR [®] s GY STAR [®] compliant config ured PC featuring a hard dis	pecifications for computers. If a urations, then energy efficiency
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	31 BTU/hr	34 BTU/hr	33 BTU/hr
Normal Operation (Long idle)	25 BTU/hr	27 BTU/hr	27 BTU/hr
Sleep	3 BTU/hr	3 BTU/hr	3 BTU/hr
Off	2 BTU/hr	2 BTU/hr	1 BTU/hr
	*NOTE: Heat dissipation is calcula attained for one hour.	ted based on the measured	watts, assuming the service level is
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)		Sound Pressure (L _{pAm} , decibels)
Typically Configured – Idle	2.9		20
Fixed Disk – Random writes	2.9		21
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:		
	Spare parts are available through of production.	out the warranty period and	l or for up to "5" years after the end
Batteries	This battery(s) in this product con	nply with EU Directive 2006/	/66/EC
	Batteries used in the product do n	ot contain:	



Technical Specifications – Environmental

Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight

Battery size: CR2032 (coin cell) Battery type: Lithium

Additional Information This product is in compliance with the Restrictions of Hazardous Substances (RoHS) • directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic • Equipment (WEEE) Directive - 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe • Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680 (EPEAT) standard at the <gold> level, • see www.epeat.net Plastics parts weighing over 25 grams used in the product are marked per ISO11469 • and ISO1043. This product contains 0% post-consumer recycled plastic (by wt.) ٠ • This product is 96.1% recycle-able when properly disposed of at end of life. **Packaging Materials** External: PAPER/Cardboard & misc 360.2 g Internal: PLASTIC/EPE (Expanded Polyethylene) 29.8 q PLASTIC/Polyethylene low density 13.6 q PLASTIC/Polypropylene 6 q The plastic packaging material contains at least 50% recycled content. The corrugated paper packaging materials contains at least 70% recycled content. This product does not contain any of the following substances in excess of regulatory limits Material Usage (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): Asbestos • Certain Azo Colorants . • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Cadmium • **Chlorinated Hydrocarbons** • **Chlorinated Paraffins** • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • • **Mercuric Oxide Batteries** Nickel – finishes must not be used on the external surface designed to be frequently • handled or carried by the user. **Ozone Depleting Substances** • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has • been voluntarily removed from most applications.

Radioactive Substances .



Technical Specifications – Environmental

	• Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	 HP follows these guidelines to decrease the environmental impact of product packaging: Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	 HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the HP web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP Inc. Corporate Environmental Information	For more information about HP's commitment to the environment: Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Desig n_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

Country of Origin

China

Options and Accessories (sold separately and availability may vary by country)

Tupo	Description	- Part #
Туре Моточи	•	Z4Y84AA
Memory	HP 4GB DDR4-2400 SODIMM (Core processors only)	
	HP 16GB DDR4-2400 SODIMM (Core processors only)	Z4Y86AA
Cases	HP Executive 15.6 Black Top Load	P6N18AA
	HP Business Case (up to 15.6")	H5M92AA
Docking	HP UltraSlim Docking Station	D9Y32AA
	HP 2013 UltraSlim Docking Station TAA (US only)	E5C22AV#ABA
	HP Executive Travel Hub	ΤΟΚ29ΑΑ
	HP Travel Hub	ТОКЗОАА
	HP 3005pr USB 3.0 Port Replicator w/ USB-C Adapter	Y4H06AA
	HP Display and Notebook Stand II	E8G00AA#xxx
	HP USB-Type C™ Elite Dock	X7W54AA
Input/Output -	HP Comfort Grip Mouse	H2L63AA
Mice	HP 3-Button Laser Mouse	H4B81AA#xxx
	HP Ultra Mobile Wireless Mouse	H6F25AA#xxx
	HP X4000 Bluetooth Mouse	H3T50AA#xxx
	HP Slim Bluetooth Mouse	F3J92AA#xxx
	HP Ultrathin Wireless Mouse	L9V78AA
	HP USB Travel Mouse	G1K28AA#xxx
	HP Slim Wireless Keyboard and Mouse	T6L04AA#xxx
	HP USB Essential Keyboard and Mouse	H6L29AA#xxx
	HP Slim USB Keyboard and Mouse	T6T83AA
	HP Wireless (Link-5) Keyboard	T6U20AA#xxx
Power Adapters	HP 65W Slim A/C Adapter w/USB	H6Y82AA
	HP 90W Slim A/C Adapter w/USB	Нбүвзаа
	HP 90W Slim Auto Combo AC Adapter w/USB	H6Y84AA
	HP 65W Smart AC Adapter	H6Y89AA
	HP 90W Smart AC Adapter	H6Y90AA
Battery	HP TA03XL Rechargeable Battery	1FN06AA
Adapters	HP USB-C™ to VGA Adapter	N9K76AA
	HP USB-C to USB 3.0	N2Z63AA
	HP USB-C to USB Hub	Z6A00AA
	HP USB-C™ to DisplayPort™ Adapter	N9K78AA
	HP USB-C™ to DisplayPort™ Adapter	N9K78AA
	HP HDMI to DVI adapter	F5A28AA
	DisplayPort™ to DVI Adapter	F7W96AA



Options and Accessories (sold separately and availability may vary by country)

	DisplayPort™ to VGA	F7W97AA
	DisplayPort™ to HDMI 1.4 Adapter	F3W43AA
Wireless	HP lt4120 LTE/EVDO/HSPA+ Gobi™ 4G Mobile Broadband Module	TBD
Collaboration	HP UC Conferencing Keyboard	K8P74AA#xxx
	HP UC Speaker Phone	K7V16AA
	HP UC Wired Headset	K7V17AA
	HP UC Mono Wireless Headset	W3K08AA
	HP UC Duo Wireless Headset	W3K09AA
	HP Stereo 3.5mm Headset	T1A66AA
	HP Stereo USB Headset	T1A67AA
Storage - Exterr	al HP External USB DVDRW Drive	F2B56AA
Storage	HP 500GB 7200rpm HDD	F3B97AA
	HP 256GB M2 NVME PCIe SSD (2280)	V3K66AA
	HP 512GB M2 NVME PCIe SSD (2280)	V3K67AA
Security	HP Dual Head Cable Lock (Non-Master key)	T1A64AA
-	HP Dual Head Cable Lock (Master Key)	T1A65AA
	HP 15.6" Notebook PC Privacy Filter (non-touch)	J7H71AA
	HP Docking Station Cable Lock	AU656AA#XXX
	HP Essential Combination Lock	T0Y16AA
	HP Combination Lock	T0Y15AA
	HP Keyed Cable Lock	T0Y14AA
	HP 15'6 Privacy Filter (touch panel)	V8Z58AA#xxx

NOTE: External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.



Summary of Changes

Date of change:	Version History:	Description of change:
	From v1 to v2	

Copyright © 2018 HP Development Company, L.P. The information contained herein is subject to change without notice. The only warranties for HP products are set forth in the express limited warranty statements accompanying such products. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein.

Intel, Core, and Celeron, Thunderbolt and vPro are registered trademarks or trademarks of Intel Corporation or its subsidiaries in the U.S. and/or other countries. Bluetooth is a registered trademark of its proprietor used by HP Inc. under license. AMD, FirePro, and Enduro are trademarks of Advanced Micro Devices, Inc. Adobe is a trademark of Adobe Systems Incorporated. Microsoft and Windows are U.S. registered trademarks of Microsoft Corporation in the United States and/or other countries. Qualcomm and Snapdragon are trademarks of Qualcomm, Inc. SD, SDHC, and SDXC are trademarks or registered trademarks of SD-3C in the United States, other countries or both. USB Type-C and USB-C are trademarks of USB Implementers Forum. ENERGY STAR[®] is a registered trademark mark of the U.S. Environmental Protection Agency.

